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Patent Abstracts of Japan

PUBLICATION NUMBER : 51126765
PUBLICATION DATE : 05-11-76

APPLICATION DATE : 25-04-75
APPLICATION NUMBER : 50050449

APPLICANT : TOSHIBA CORP;

INVENTOR : MORIGUCHI HIROSHI;

INT.CL. : H01L 21/56

TITLE : RESIN SEALED SEMICONDUCTOR UNIT MANUFACTURING PROCESS

ABSTRACT : PURPOSE: To prevent resin seal layer from cracking and thus to eliminate gaps from resin sealed semiconductor unit.

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